

Application No.
10/569,942

Group	2812
Unknown	

FILING DATE
IF APPROPRIATE

TRANSLATION
YES NO

U.S. Patent Application No. 11/851,065 (NISHIHATA et al.), which was filed on September 6, 2007 and entitled, "BONDED WAFER AND METHOD OF MANUFACTURING THE SAME."

DATE CONSIDERED 07/28/2008

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